

May 13, 2026

BSE Limited

Corporate Relationship Dept.,
14th floor, P. J. Tower,
Dalal Street, Fort
Mumbai - 400 001

National Stock Exchange of India Limited

Exchange Plaza, Plot no. C/1, G Block,
Bandra-Kurla Complex,
Bandra (E),
Mumbai - 400 051

Scrip Code – 543664

Scrip Symbol – KAYNES

Dear Sir/Madam,

Subject: Investors/ Earnings Presentation under Regulation 30 of SEBI (Listing Obligations and Disclosure Requirements) Regulations, 2015.

With reference to Regulation 30 of the SEBI (Listing Obligations and Disclosure Requirements) Regulations, 2015, please find enclosed the Investors/ Earnings Presentation for the Quarter and Year ended March 31, 2026. The Company will use this presentation for any meeting scheduled with analysts or institutional investors up to June 30, 2026.

The above information will also be available on the website of the Company at www.kaynes technology.co.in.

Request to kindly take this intimation on record.

Thanking You,

Yours faithfully,

For Kaynes Technology India Limited

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SUDHASRI
Digitally signed by
ADDEPALLI
SUDHASRI
Date: 2026.05.13
23:16:54 +05'30'

Sudhasri Addepalli

Company Secretary and Compliance Officer
ICSI Membership No: ACS 79832

Enclosed: As above

KAYNES TECHNOLOGY INDIA LIMITED

CIN: L29128KA2008PLC045825

Website: www.kaynes technology.co.in Email ID: kaynes techcs@kaynes technology.net

H.O & Regd Office: 23-25, Belagola, Food Industrial Estate Metagalli PO, Mysore 570016, Karnataka, India

Telephone No: +91 8212582595



Kaynes Technology India Limited

Investor Presentation | May 2026

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Financial Highlights

FY26 Results Snapshot (Consolidated)



₹ 47,271 mn
Networth
₹ 28,373 mn as of Mar-25



₹ 36,264 mn
Revenue
33% YoY



₹ 5,741 mn
EBITDA
40% YoY



15.8%
EBITDA Margin
70 bps YoY



₹ 3,639 mn
Profit After Tax
24% YoY



10.0%
PAT Margin
-80 bps YoY



₹ 83,663 mn
Order Book
₹ 65,969 mn as of Mar-25



₹ 2,074 mn
Net Debt
₹ 5,813 mn as of Mar-25



13.1%
ROCE*
19.2% in Mar-25



11.4%
ROE*
19.4% in Mar-25



125 Days
Net working capital days
87 days in Mar-25



0.0
Net Debt* to Equity
0.2 as of Mar-25

*ROCE, ROE and Net debt are adjusted for unutilized IPO & QIP proceeds.

Q4FY26 Results Snapshot (Consolidated)



₹ 12,426 mn

Revenue
26% YoY



₹ 1,937 mn

EBITDA
15% YoY



15.6%

EBITDA Margin
-150 bps YoY



₹912 mn

Profit After Tax
-21% YoY



7.3%

PAT Margin
-450 bps YoY

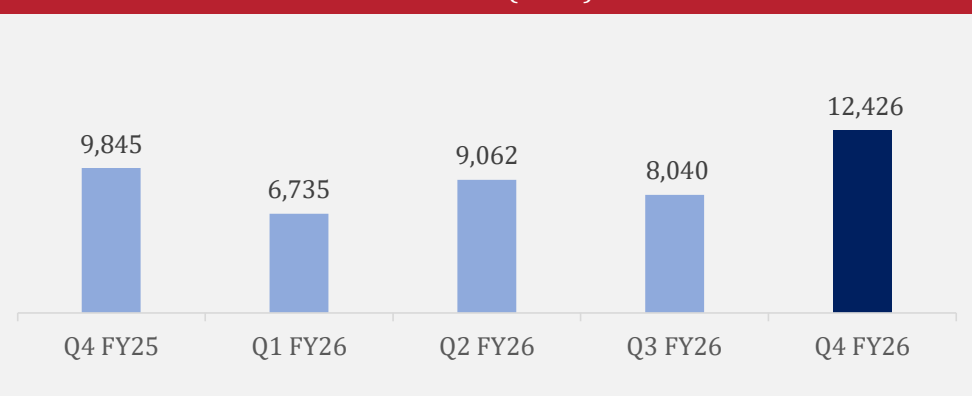


₹409 mn

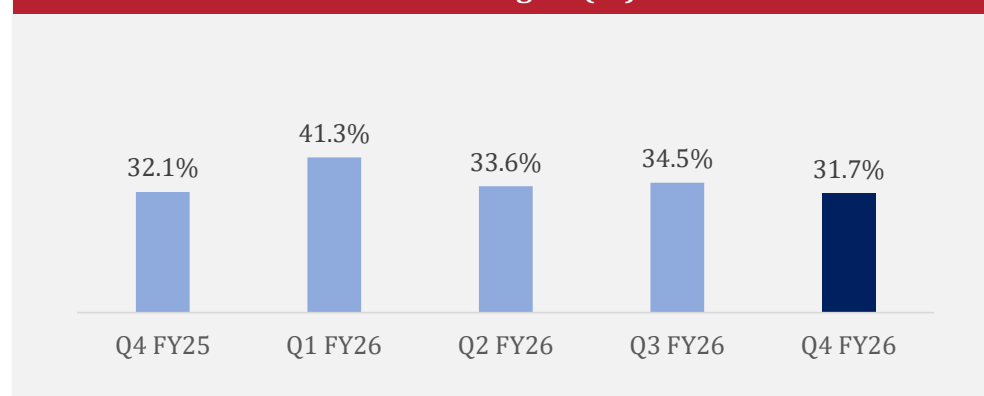
Finance Cost
39% YoY

Consistent quarterly financial performance – Q4FY26

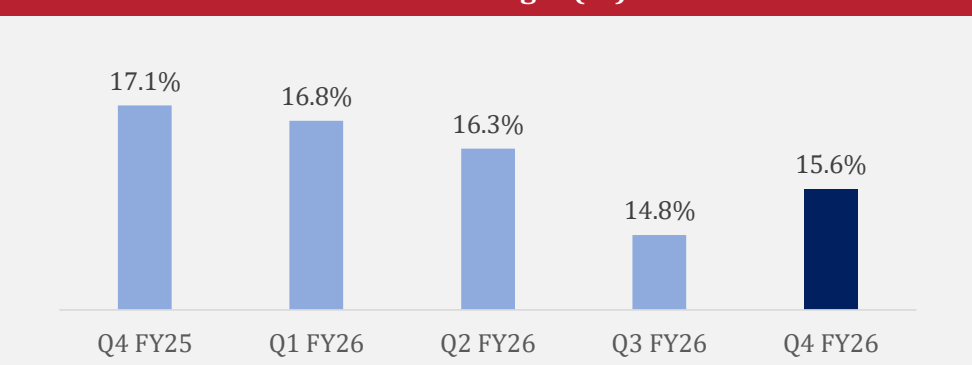
Revenue (₹ Mn)



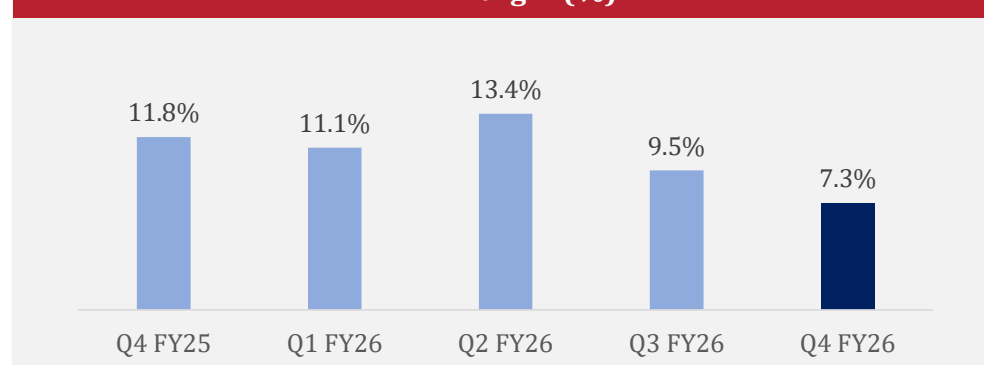
Gross Margins (%)



EBITDA Margin (%)



PAT Margin (%)



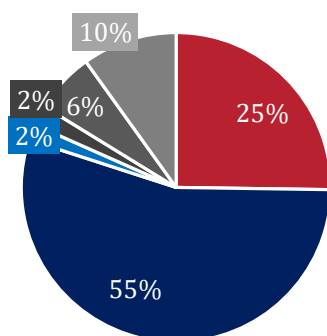
Diversified Revenue Mix



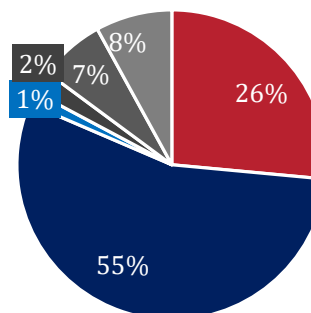
FY26

Revenue across verticals

FY25



- Automotive
- Industrial incl EV
- Aerospace, Outer-space & Strategic Electronics
- Medical
- Railways
- IoT / IT, Cons and Others

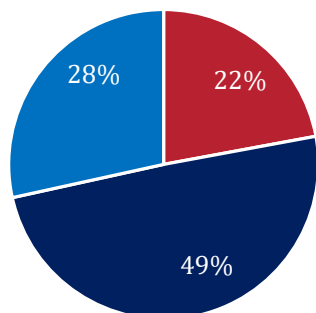


- Automotive
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- Aerospace, Outer-space & Strategic Electronics
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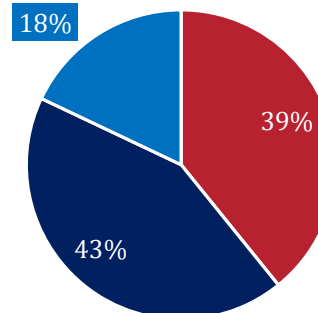
FY26

Revenue across Segments

FY25



- OEM - Turnkey - Box Build
- OEM - Turnkey - PCBA
- ODM & Prod. Eng. and IoT solutions

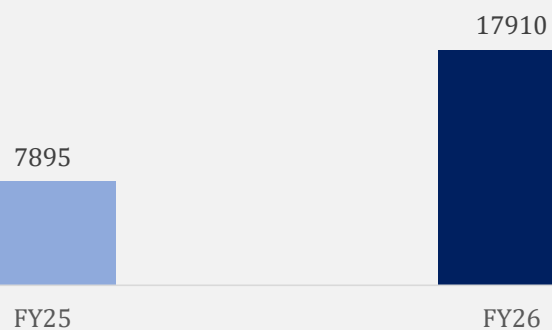


- OEM - Turnkey - Box Build
- OEM - Turnkey - PCBA
- ODM & Prod. Eng. and IoT solutions

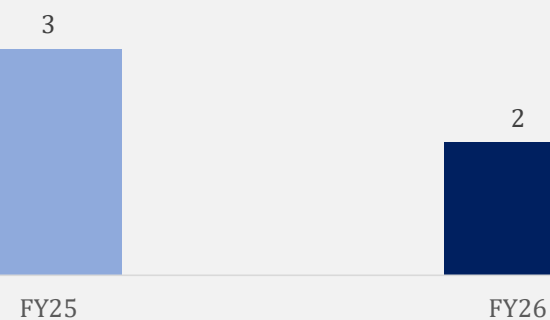
Annual financial performance



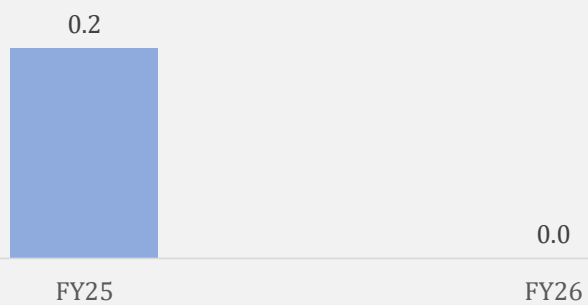
Gross Block (₹ Mn)



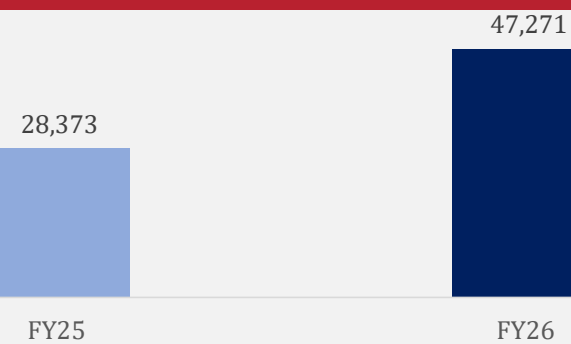
Asset Turnover ratio (x)



Net Debt/Equity (x)



Networth (₹ Mn)

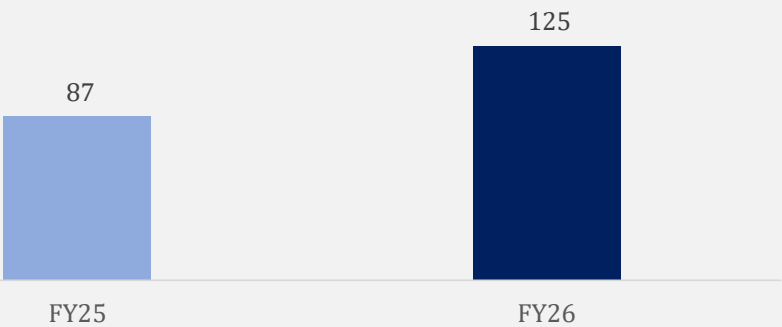


Note: Asset Turnover Ratio is annualized

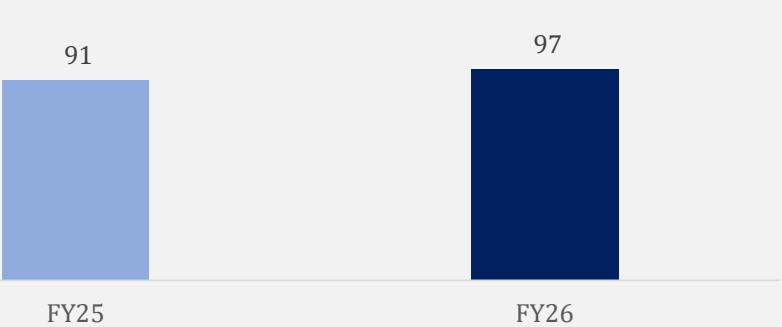
Annual financial performance



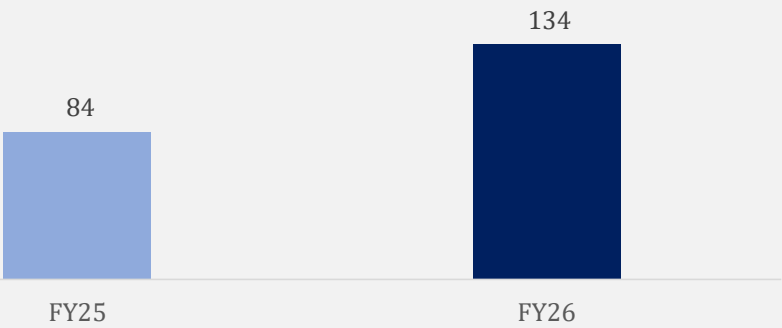
Net Working Capital Days



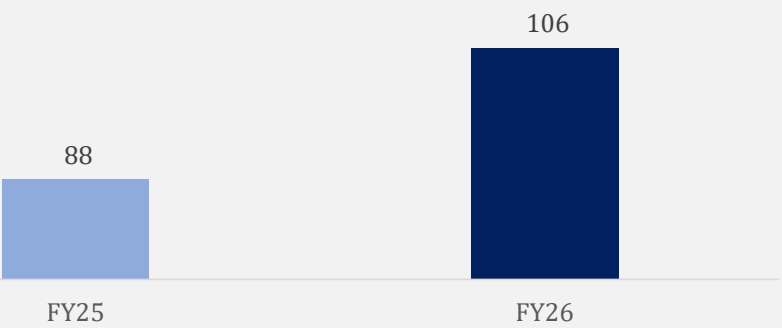
Inventory Days



Receivable Days



Payable Days



Q4 and FY26 Profit & Loss Statement (Consolidated)



Particulars (₹ Mn)	Q4 FY25	Q4 FY26	YoY	FY25	FY26	YoY
Revenue from operations	9,845	12,426	26.2%	27,218	36,264	33.2%
Raw material cost	6,687	8,485	26.9%	18,997	23,719	24.9%
Employee expenses	466	908	94.7%	1,781	3,136	76.1%
Other expenses	1,014	1,097	8.2%	2,333	3,669	57.3%
EBITDA	1,679	1,937	15.4%	4,107	5,741	39.8%
EBITDA margin (%)	17.1%	15.6%	(150 BPS)	15.1%	15.8%	70BPS
Depreciation and amortization expense	169	544	221.3%	447	1,071	139.3%
Other income	205	419	104.5%	1,070	1,568	46.6%
Finance cost	295	409	38.7%	1,013	1,169	15.4%
Exceptional items	-	(0)	NA	-	(26)	NA
Profit before tax (after exceptional items)	1,419	1,402	-1.2%	3,716	5,043	35.7%
Total tax expenses	257	490	90.5%	782	1,404	79.6%
Net profit after tax	1,162	912	-21.5%	2,934	3,639	24.0%
Net profit margin (%)	11.8%	7.3%	(450 BPS)	10.8%	10.0%	(80BPS)

Profit & Loss Statements (Consolidated)



Particulars (₹ Mn)	FY24	FY25	FY26
Revenue from operations	18,046	27,218	36,264
Raw material cost	13,299	18,997	23,719
Employee expenses	1,028	1,781	3,136
Other expenses	1,178	2,333	3,669
EBITDA	2,542	4,107	5,741
EBITDA margin (%)	14.1%	15.1%	15.8%
Depreciation and amortization expense	251	447	1,071
Other income	559	1070	1,568
Finance cost	534	1013	1,169
Exceptional items	-	-	(26)
Profit before tax (after exceptional items)	2,316	3,716	5,043
Total tax expenses	483	782	1,404
Net profit after tax	1,833	2,934	3,639
Net profit margin (%)	10.2%	10.8%	10.0%

Balance Sheets (Consolidated)



Particulars (₹ Mn)	FY24	FY25	FY26
Gross Block (tangible assets)	3,276	6,263	13,320
Accumulated Depreciation	682	1,218	2,223
Net Block (tangible assets)	2,594	5,045	11,097
Intangible assets	620	2,381	5,364
Other non-current assets	3,571	12,154	14,006
Total non-current assets	6,785	19,580	30,467
Inventories	5,483	8,144	11,032
Trade receivables	3,556	5,746	15,276
Cash and cash equivalents	15,256	10,563	7,986
Other current assets	1,572	2,379	4,179
Total current assets	25,867	26,832	38,473
Total Assets	32,652	46,412	68,940
Borrowings	112	675	3,370
Other non-current liabilities	293	474	673
Total non-current liabilities	405	1,149	4,043
Short-term borrowings	2,949	8,080	5,379
Trade payables	3,610	6,829	8,508
Other current liabilities	803	1,912	3,386
Total Current Liabilities	7,362	16,821	17,273
Total Equity & Reserves	24,885	28,442	47,625
Total Equity and Liabilities	32,652	46,412	68,940

Cash Flow Statements (Consolidated)

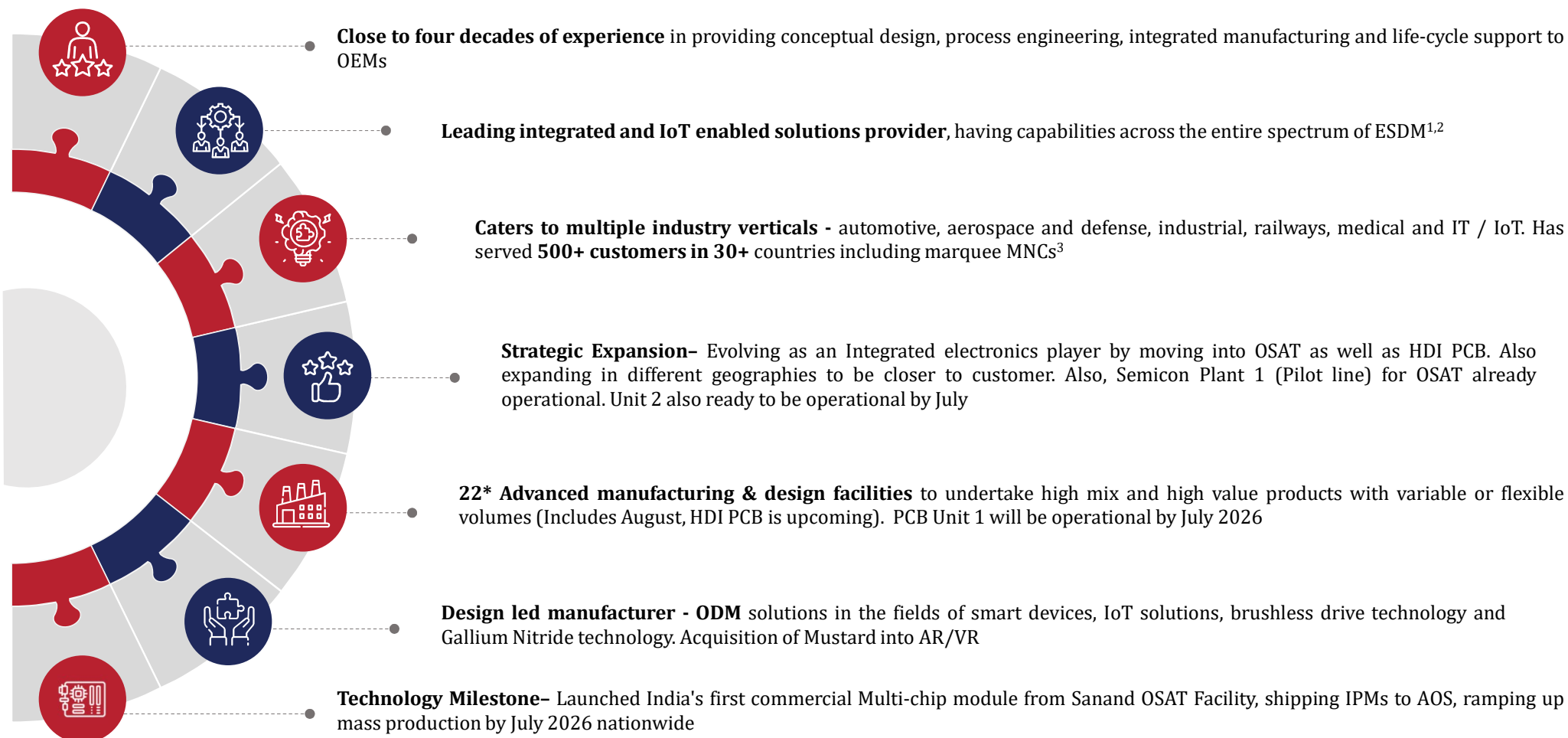


Particulars (₹ Mn)	FY24	FY25	FY26
Cash flow from operating activities			
Profit before tax	2,316	3,716	5,043
Adjustment for non-operating items	401	626	1,674
Operating profit before working capital changes	2,717	4,343	6,717
(Increase)/ decrease in inventories	-1,352	-2,661	(2,888)
(Increase)/decrease in trade receivables	-1,420	-2,190	(10,239)
(Increase)/decrease in payables & other adjustments	1,238	329	1,804
Cash generated from operations	1,183	-179	(4,605)
Less: direct taxes paid	-481	-644	(1,399)
Net cash from operating activities	701	-823	(6,004)
Cash flow from investing activities	-15,052	-3,547	(9,172)
Cash flow from financing activities	14,286	4,650	15,796
Net increase/ (decrease) in cash & cash equivalent	-65	280	620
Add: Cash and cash equivalents as at 1st April	259	194	474
Add: Net effect of exchange gain on cash and cash equivalents	0	0	0
Cash and cash equivalents as at 31st march	194	474	1,094



Company Overview

Company Overview



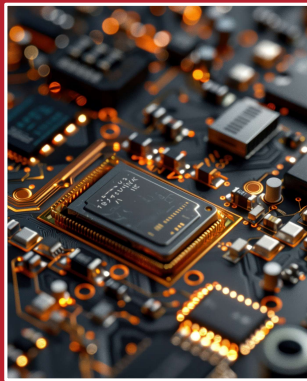
1 – Electronic System & Design Manufacturer; 2- As per Care Edge report; 3 – As of FY25, 22*- HDI PCB is upcoming (OSAT Unit 1 is now operational)

Leading integrated Electronics player in India



With backward integration into PCB and vertical integration in OSAT

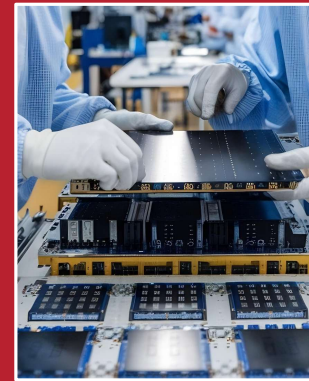
Well Positioned to deliver comprehensive and integrated solutions to customers



Printed Circuit Board



EMS



OSAT
(Assembly Testing Packaging)

Better involvement in the larger electronics supply chain, spanning across wafer to end user product

We are fundamentally redefining our position in the ESDM ecosystem. The strategic integration of our core EMS expertise with advanced OSAT and PCB manufacturing capabilities creates an unparalleled competitive moat. This integrated approach grants Kaynes complete, predictive visibility across the full electronics supply chain, enabling us to accelerate time-to-market for clients and strategically advance toward becoming a fully integrated electronics ODM

Diversified product portfolio

Automotive	Industrial & EV	Railways	Medical	Aerospace, Outerspace & Strategic electronics	IOT/IT, Cons and others
Cluster PCBA  LED Headlamp/Tail Lamp/LED Position Lamp/DRL PCBA  Switches PCBA¹  BCU Master / BCU Slave PCBA 	Engine Control Panel  Street light controller  Smart Energy Meter  Precision Bridge and Strain Gage 	UM71 - Receiver  ETCS cubicle  SDTC cubicle  SDTC Card File 	Endoscopy cart & ICP sensor module  X-ray & Dental X-ray machine  Controller Units  Protein & clinical chemistry analyzers 	HH Sonar  Mission Critical Products²  ESAF  ATE & LRU Cable Assemblies 	Bar Code Scanner & RFID gateway  PLC & Asset Condition Monitoring gateway  Sensors  Industrial HMI Reader & Industrial Tablet 

1 - Headlamp level switch / Steering control switch/ Windowlift Motor/ Rocker Switch PCBA | 2 - Kaynes has been a valuable industry partner for soft landing of Chandrayaan-3 & launch of Aditya-L1 missions

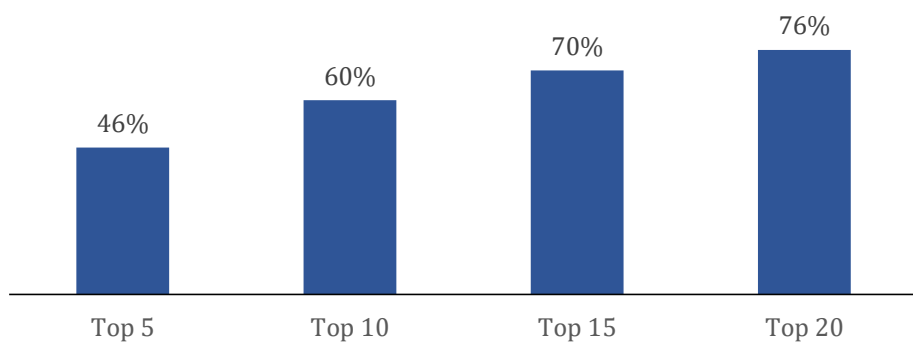
Marquee customer base



Industry	 Industrial	 Railways	 Automotive	 Medical	 Aerospace+ Others ¹	 IoT / IT and others
Key Customers	Leading global mfg of electronic instruments and electromechanical devices	  		 	 	

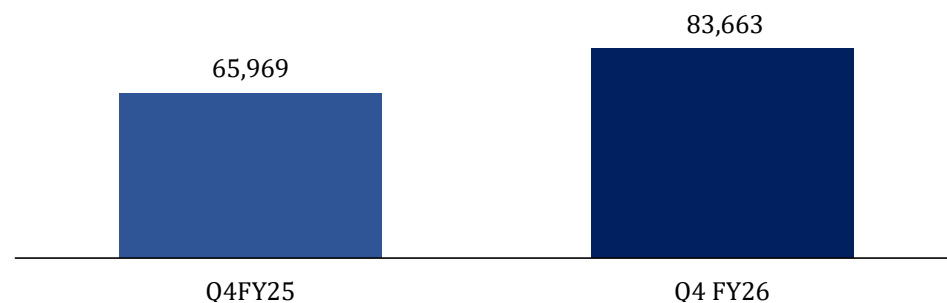
Low customer concentration

FY26



Strong order book

INR Mn



R&D & Engineering, Certifications and Supply Chain



Research and Development

Focused on development of new products and improvement existing products

Dedicated research facility at Mysore, Bangaluru & Ahmedabad with a 200+ member R&D & Engineering Team¹

Operations complying with global standards with 13 global accreditations –most for an ESDM company in India^{1,3}

Facilities approved by global certifications Agencies E.g. Underwriters Laboratories, CSA2, TUV Rhineland



Certifications

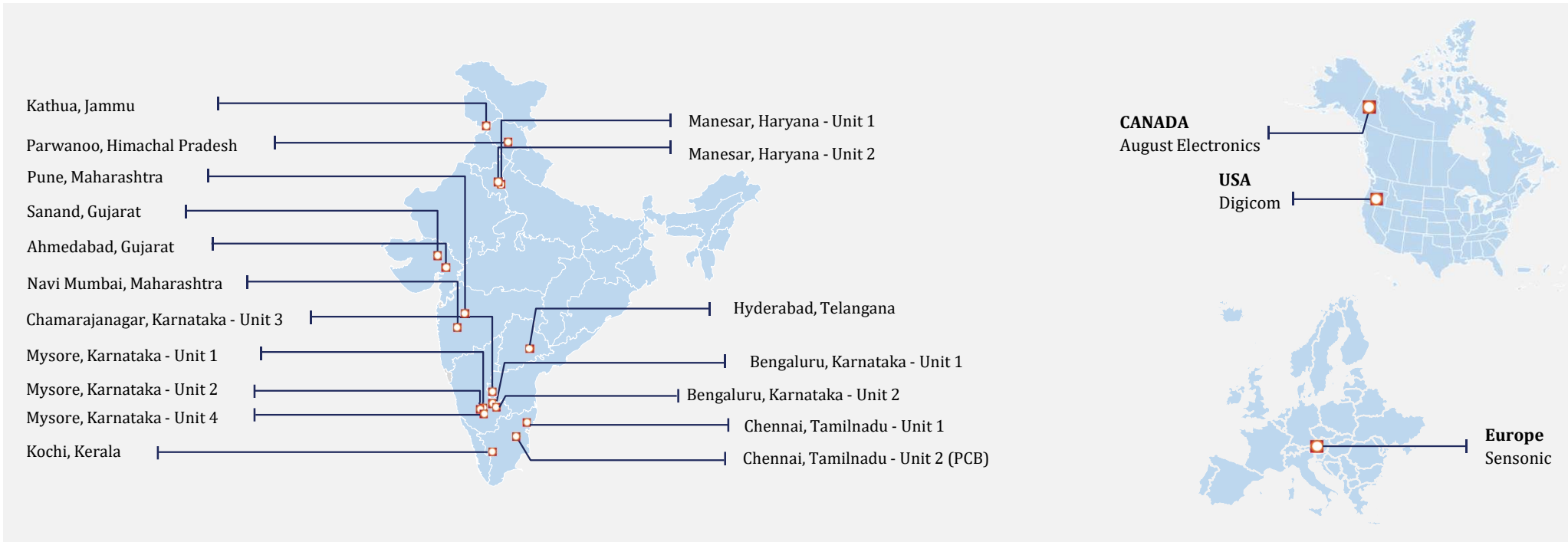


Supply chain

Long term relationship with suppliers leading to better credit terms

Suppliers with multiple sources for a single component with specialized dealers for niche verticals

Capacity for Manufacturing at Local & Global Scale Augmented by Technical Capabilities



25+ SMT Lines	70 THD Lines	26 Cable Harness Lines	15 plastic molding machines	10K class clean room
Commissioning of the Pilot Line/Unit 1 for OSAT	Most manufacturing at low-cost locations	Dedicated humidity-controlled stores	Fungible infrastructure	2 exclusive RoHS compliant lines for green manufacturing

Kaynes Expansion – Chamaraajanagar



- Built-up area of ~ 350K sq ft
- Well supported by ancillary facilities of existing units / expansion plans
- Phase-I: Alpha & Beta Ready (~100K sq ft)
- Phase-II:
 - Gamma ready for operations i.e. ~240,000 Sq feet
 - Clean Room of Class 10K
 - Wire Bonding
 - Box Build
 - Aerospace vertical

Kaynes Expansion – Hyderabad



- Location: Kongara Kalan (Near Hyderabad Airport)
- Total Plant Area: 70K SFT
- SMT Lines -1 Number
- Plastic Injection Machines- 29 NOS (80 -350 TON)
- Upcoming new plant 150K SFT



Backward integration – OSAT & HDI PCB subsidiaries



- Built-up area Unit 1 – Plant 1 area of ~ 2,1000 Sq ft
- Built up area Unit 1- Plant 2 area of ~ 241K Sq ft
- Phase 2 Expansion- 236K Sq ft
- Key Packages include:
 - Legacy packages: QFN, TO
 - Semi- Advance Packages: BGA, Flip Chip BGA
 - Advance Packages: 2D, 2.5D, 3 D along with Co-Package Optics
- Key Areas of Usage:
 - Power electronics for Automotive, Healthcare, Industrial
 - Consumer goods
 - Wireless devices & IoT

Kaynes Circuits – Chennai

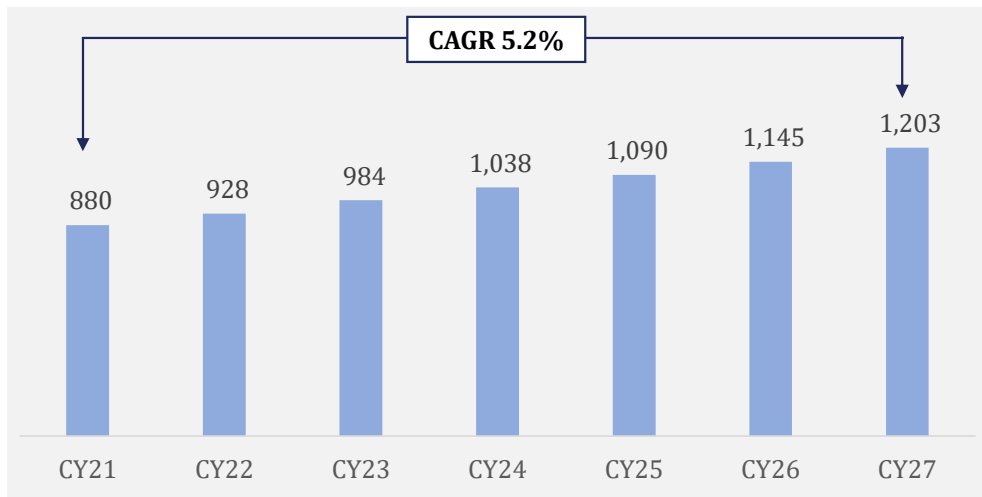


- 1. About 5 Million SQ MT of PCB Manufacturing Capacity in India
- 2. Multi Layer PCB both Rigid and Rigid Flex (High Layer Count Printed Circuit Boards, of up to 74 layers).
- 3. HDI PCB (High Density Interconnect Boards)
- 4. Flexible PCB (up to 16 layers.)
- Key Areas of Usage:
 - Telecom
 - Medical
 - Auto- EV
 - Strategic sectors
 - Smart Phones

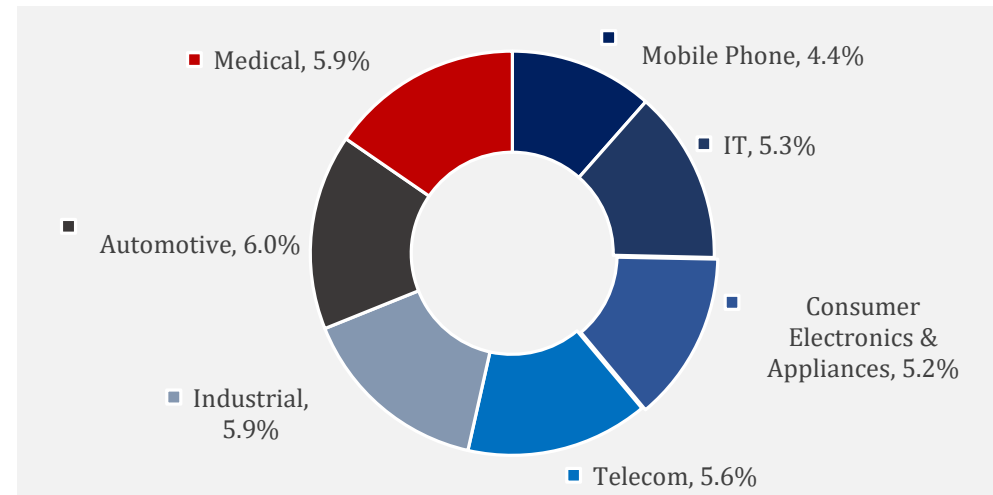
Industry Overview

Industry Update (ESDM)

Global ESDM Market Size (US \$ BN)



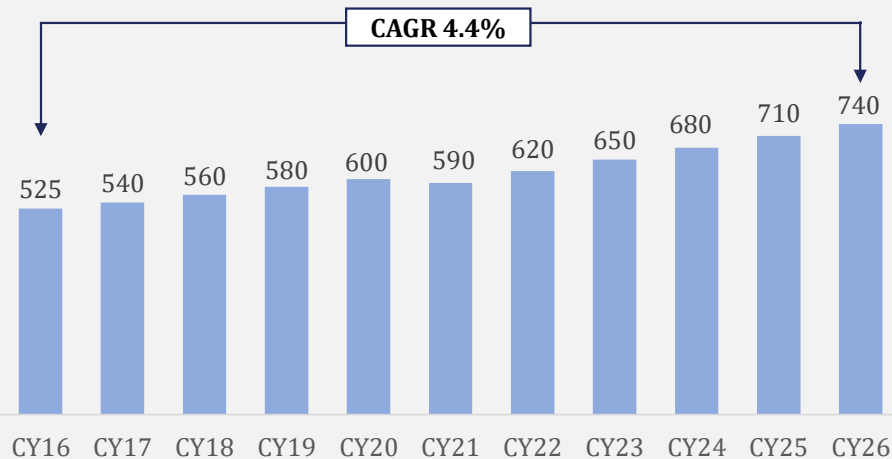
Global ESDM Segment CAGR from CY 2023 to CY 2027 (E)



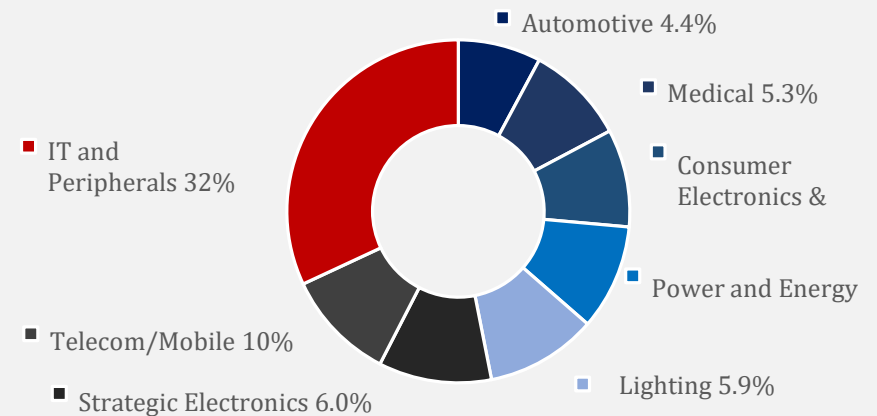
- The global Electronic System Design and Manufacturing (ESDM) industry is undergoing a significant shift from traditional OEM-led production to integrated system-level partnerships.
- Companies operating within the ESDM value chain are increasingly providing end-to-end solutions across the product lifecycle—encompassing design, prototyping, assembly, testing, and post-sales support.
- Robotic manufacturing, smart factories, and real-time data analytics are transforming productivity and efficiency in global ESDM
- Growth in decentralized computing architectures necessitates the development of high-performance but energy-efficient hardware for real-time processing at network edges

Industry Update (PCBA)

Global PCBA Industry Market Size (US \$ BN)



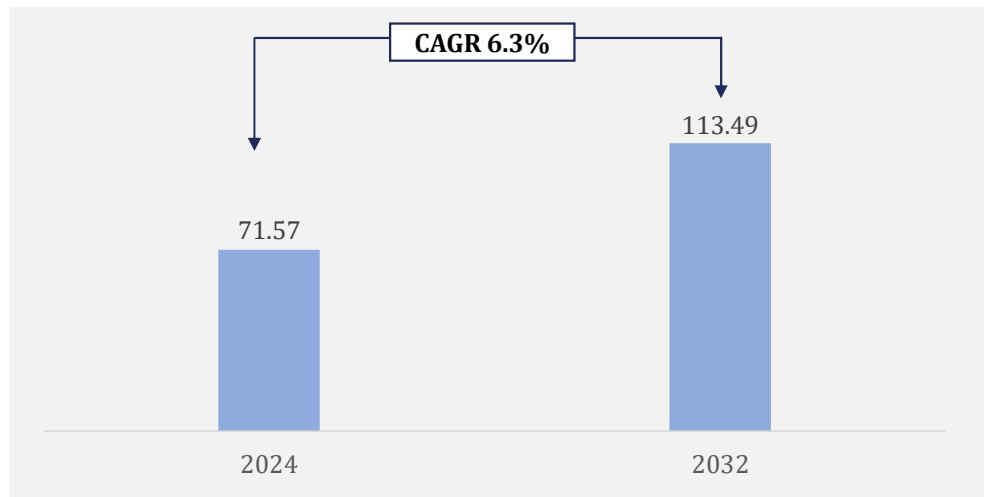
Global PCBA Market Share by Industry



- The significant growth in PCBA underscores the industry's widespread relevance across various end-user domains such as telecommunications, IT hardware, automotive, consumer electronics, medical equipment, and other strategic sectors.
- PCBAs cater to both large-scale consumer products and specialized, low-volume applications that require high precision and reliability. As the central hub for integrating electronic components, the PCBA sector serves as a cornerstone of the global electronics manufacturing landscape.
- With devices becoming increasingly compact, intelligent, and interconnected, the demands on PCBA complexity and performance have grown substantially. This has amplified their role not just in assembling final products, but also in driving innovation, ensuring quality, and enhancing functional efficiency across a broad range of technologies.

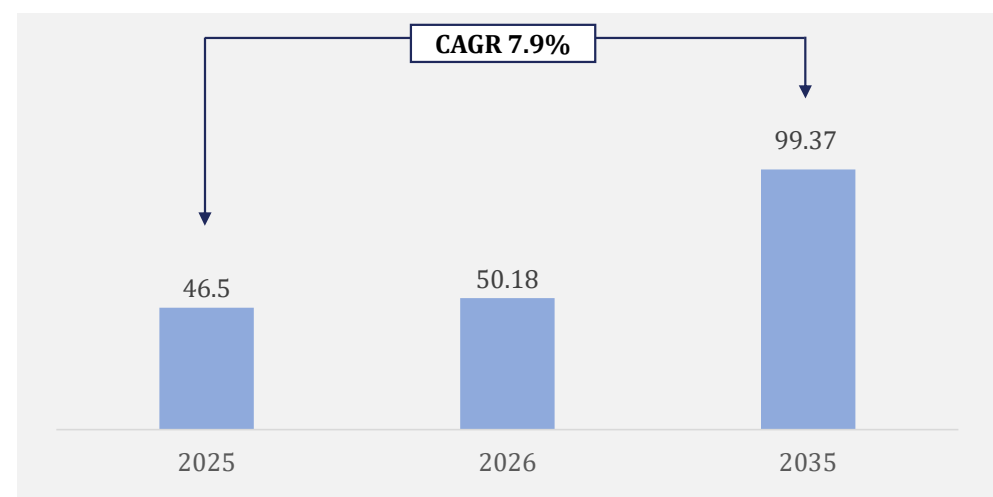
Source: Annual Report FY25

Global PCB Industry Market Size (US \$ bn)¹



- Demand driven by key factors such as growth in consumer electronics, industrial automation, and applications across automotive, telecommunication, healthcare, and energy.
- After COVID-19 disruptions, the market rebounded due to increased sales and prices, while advances in display technologies and flexible PCBs fuel long-term growth.
- India's PCB market is booming, projected to grow from USD 6.3 billion in 2024 to USD 24.7 billion by 2033 at a blistering CAGR of 15.6%—far outpacing global averages.
- This growth is fueled by government incentives (PLI, Make in India), localization of electronics supply chains, and telecom (5G) infrastructure, and a surge in advanced multilayer and flexible PCB technologies.

Global OSAT Industry Market Size (US \$ bn)



- While the Asia-Pacific region dominates with over 70% market share due to established supply chains, North America is witnessing growth through reshoring initiatives.
- The Indian OSAT market is expected to grow at 8–15% CAGR (using different data sets), benefiting from booming electronics consumption, strategic partnerships with global players, and an increasing focus on advanced packaging technologies such as System-in-Package (SiP), 2.5D/3D, and fan-out panel-level packaging

COMPANY :



Kaynes Technology India Limited
CIN: L29128KA2008PLC045825
Name: Mr. Jairam P Sampath
Whole-time Director & Chief Financial Officer
Email: ir@kaynestechology.net
Website: www.kaynestechology.co.in

INVESTOR RELATIONS ADVISORS :



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MUFG Pension & Market Services

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Meeting Request [Link](#) 

THANK YOU